

Wk
area between the main surface of the semiconductor chip and
the main surface of the resin seal member.

IN THE CLAIMS

Rewrite claim 7 and add new claim 8 as follows:

R2
7. (Amended) A semiconductor device according to claim
4, wherein the main surface of the semiconductor chip is
formed in a rectangular shape in which the first and second
sides of the main surface of the semiconductor chip are a long
side and a short side, respectively.

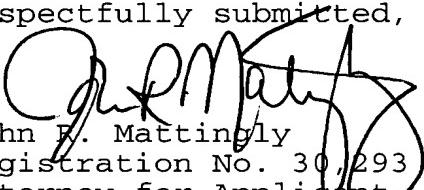
R3
8. (New) A semiconductor device according to claim 4,
wherein the main surface of the semiconductor chip is formed
in a rectangular shape in which the first and second sides of
the main surface of the semiconductor chip are a short side
and a long side, respectively.

REMARKS

Claim 7 has been amended to correct an inadvertent error,
and claim 8 was unintentionally omitted from the application
and has been added.

Examination is requested.

Respectfully submitted,


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